

Features

- 650V GaN enhancement-mode transistor
- Normally-off design
- No Q_{rr} (reverse recovery charge)
- Low Q_g (gate charge), low Q_{oss} (output charge)
- Integrated ESD protection

Applications

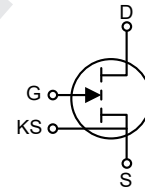
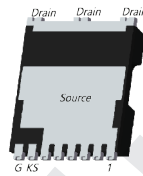
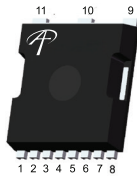
- PFC and PWM stages (LLC, FSFB, TTF) of Server, Telecom, Industrial, UPS, and Solar Inverters

Product Summary at $T_J = 25^\circ\text{C}$

$V_{DS, \max}$	650V
$R_{DS(on), \max} @ V_{GS} = 6V$	70m Ω
$Q_{g, \text{typ}} @ V_{DS} = 400V$	8.5nC
I_D, pulse	60A
$Q_{oss} @ V_{DS} = 400V$	94.7nC
$Q_{rr} @ V_{DS} = 400V$	0nC



Pin Configuration



Pin Information

Gate	Drain	Kelvin Source	Source
8	9, 10, 11	7	1, 2, 3, 4, 5, 6

Ordering Information

Ordering Part Number	Package Type	Form	Shipping Quantity
AOTL070V65GA1	TOLL	Tape and Reel	1500

Contact local sales office for full product datasheet.

Absolute Maximum Ratings

($T_J = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter		AOTL070V65GA1	Units
$V_{DS, \max}$	Drain Source Voltage	$V_{GS}=0V$, $T_J=-55^\circ\text{C}$ to 150°C	650	V
$V_{DS, \text{trans}}$	Drain Source Voltage Transient ⁽¹⁾	$V_{GS}=0V$	800	
$V_{DS, \text{pulse}}$	Drain Source Voltage Pulsed ⁽²⁾	$T_C=25^\circ\text{C}$, total time < 10 hours $T_C=125^\circ\text{C}$, total time < 1 hour	750	
I_D	Continuous Drain Current	$T_C=25^\circ\text{C}$	26	A
		$T_C=125^\circ\text{C}$	17	
$I_{D, \text{pulse}}$	Pulsed Drain Current ⁽³⁾	$T_C=25^\circ\text{C}$, $V_{GS}=6V$, $t_{\text{pulse}}=10\mu\text{s}$ $T_C=125^\circ\text{C}$, $V_{GS}=6V$, $t_{\text{pulse}}=10\mu\text{s}$	60 31	
V_{GS}	Gate Source Voltage, Continuous	$T_J=-55^\circ\text{C}$ to 150°C	-6 to 7	V
$V_{GS, \text{pulse}}$	Gate Source Voltage, Pulsed	$T_J=-55^\circ\text{C}$ to 150°C , $t_{\text{pulse}}=50\text{ns}$, $f=100\text{kHz}$, open drain	-20 to 10	V
P_{tot}	Power Dissipation ⁽⁴⁾	$T_C=25^\circ\text{C}$	231	W
$T_{J, \text{stg}}$	Junction and Storage Temperature Range		-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ	Max	Note	Units
$R_{\theta JA}$	Thermal Resistance Junction-to-Ambient ⁽⁵⁾	56.5			°C/W
$R_{\theta JC}$	Thermal Resistance Junction-to-Case	0.54	0.65		°C/W
T_{sold}	Maximum Reflow Soldering Temperature	260		MSL3	°C

Electrical Characteristics

($T_J = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 40\text{mA}$	$T_J = 25^\circ\text{C}$ $T_J = 150^\circ\text{C}$	1.2 1.6	1.7 2.5	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS} = 650\text{V}$, $V_{GS} = 0\text{V}$	$T_J = 25^\circ\text{C}$ $T_J = 150^\circ\text{C}$	1 10	65	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS} = 6\text{V}$, $V_{DS} = 0\text{V}$, $T_J = 25^\circ\text{C}$		110		μA
$R_{DS(on)}$	Drain-Source On-State-Resistance	$V_{GS} = 6\text{V}$, $I_D = 10\text{A}$	$T_J = 25^\circ\text{C}$ $T_J = 150^\circ\text{C}$	53 122	70	m Ω
DYNAMIC						
C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = 400\text{V}$, $f = 100\text{kHz}$		300		pF
C_{oss}	Output Capacitance			135		
C_{rss}	Reverse Transfer Capacitance			2.3		
$C_{o(er)}$	Effective Output Capacitance Energy Related ⁽⁶⁾	$V_{GS} = 0\text{V}$, $V_{DS} = 0$ to 400V		190		pF
$C_{o(tr)}$	Effective Output Capacitance Time Related ⁽⁷⁾			240		
R_G	Gate Resistance	$f = 5\text{MHz}$, open drain		1.4		Ω
SWITCHING						
Q_G	Gate Charge	$V_{GS} = 0$ to 6V , $V_{DS} = 400\text{V}$, $I_D = 10\text{A}$		8.5		nC
Q_{GS}	Gate Source Charge			0.7		
Q_{GD}	Gate Drain Charge			3.6		
V_{plat}	Gate Plateau Voltage	$V_{DS} = 400\text{V}$, $I_D = 10\text{A}$		2.3		V
Q_{oss}	Output Charge	$V_{GS} = 0\text{V}$, $V_{DS} = 0$ to 400V		94.7		nC
$t_{d(on)}$	Turn-On Delay Time	$V_{DS} = 400\text{V}$, $I_D = 10\text{A}$, $L_{parasitic} = 8\text{nH}$, $V_{GS} = 6\text{V}$, $R_{on} = 10\Omega$, $R_{off} = 2\Omega$, $L = 350\mu\text{H}$, $L_p = 8\text{nH}$ FWD: AOTL070V65GA1		10		ns
$t_{d(off)}$	Turn-Off Delay Time			7		
t_r	Rise Time			9		
t_f	Fall Time			9		

Electrical Characteristics (Continued)

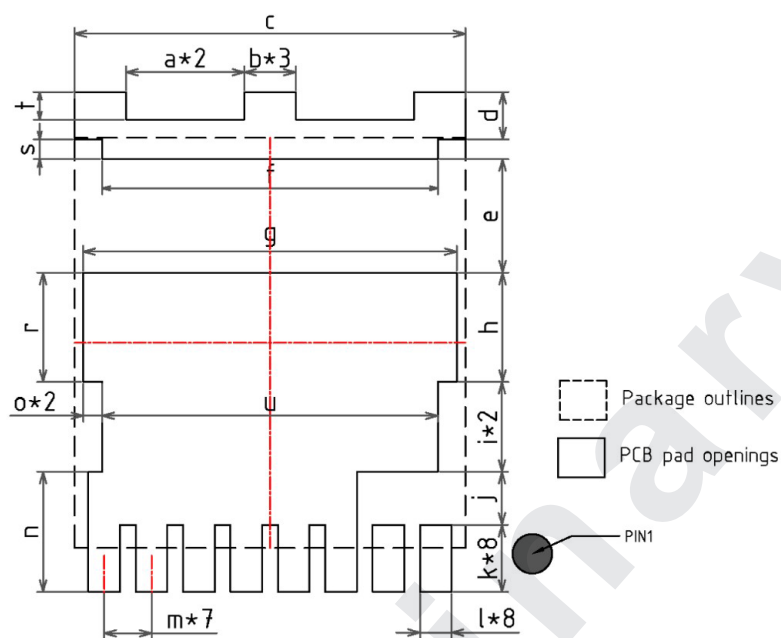
($T_J = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
REVERSE CONDUCTION						
V_{SD}	Source-Drain Reverse Voltage	$V_{GS} = 0\text{V}$, $I_S = 10\text{A}$, $T_J = 25^\circ\text{C}$		2.4		V
$I_{S, \text{pulse}}$	Reverse Pulsed Current	$V_{GS} = 6\text{V}$, $t_{\text{pulse}} = 10\mu\text{s}$			58	A
Q_{rr}	Reverse Recovery Charge	$V_R = 400\text{V}$, $I_S = 10\text{A}$, $dv/dt = 1\text{kA}/\mu\text{s}$		0		nC
t_{rr}	Reverse Recovery Time			0		ns
I_{rrm}	Peak Reverse Recovery Current			0		A

Notes:

- $V_{DS, \text{transient}}$ is intended for non-repetitive events, $t_{\text{PULSE}} < 200\mu\text{s}$.
- $V_{DS, \text{pulse}}$ is intended for repetitive pulse, $t_{\text{PULSE}} < 100\text{ns}$.
- Limit was extracted from characterization test, not measured during production.
- Power dissipation, and consequently max. current ratings are obtained using max. thermal resistance and max. temperature of 150°C .
- R_{thJA} is determined with the device mounted on one square inch of copper pad, single layer 2oz copper on FR4 board.
- $C_{O(er)}$ is the fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 400 V.
- $C_{O(tr)}$ is the fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 400 V.

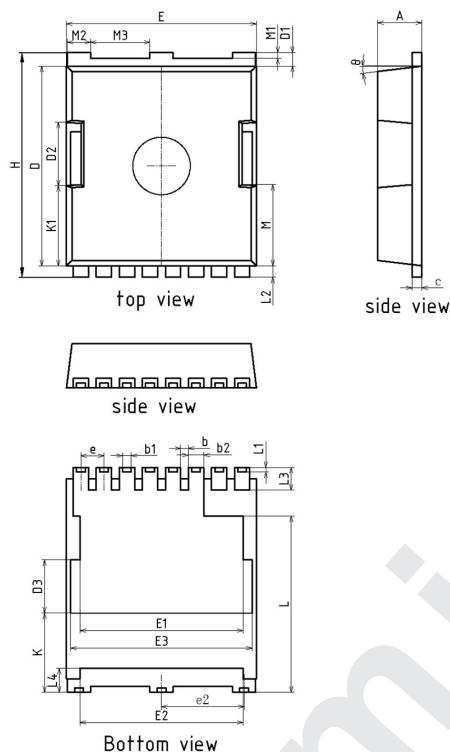
Recommended PCB Footprint



SYMBOL	DIMENSION	SYMBOL	DIMENSION
a	3.00	k	1.70
b	1.30	l	0.80
c	9.90	m	1.20
d	1.20	n	3.05
e	2.88	o	0.48
f	8.50	r	2.77
g	9.46	s	0.50
h	2.77	t	0.70
i	2.28	u	8.50
j	1.35	/	/

Notes:
 (1) All dimension are in millimeters.
 (2) Drawing is not to scale.

Package Dimensions, TOLL

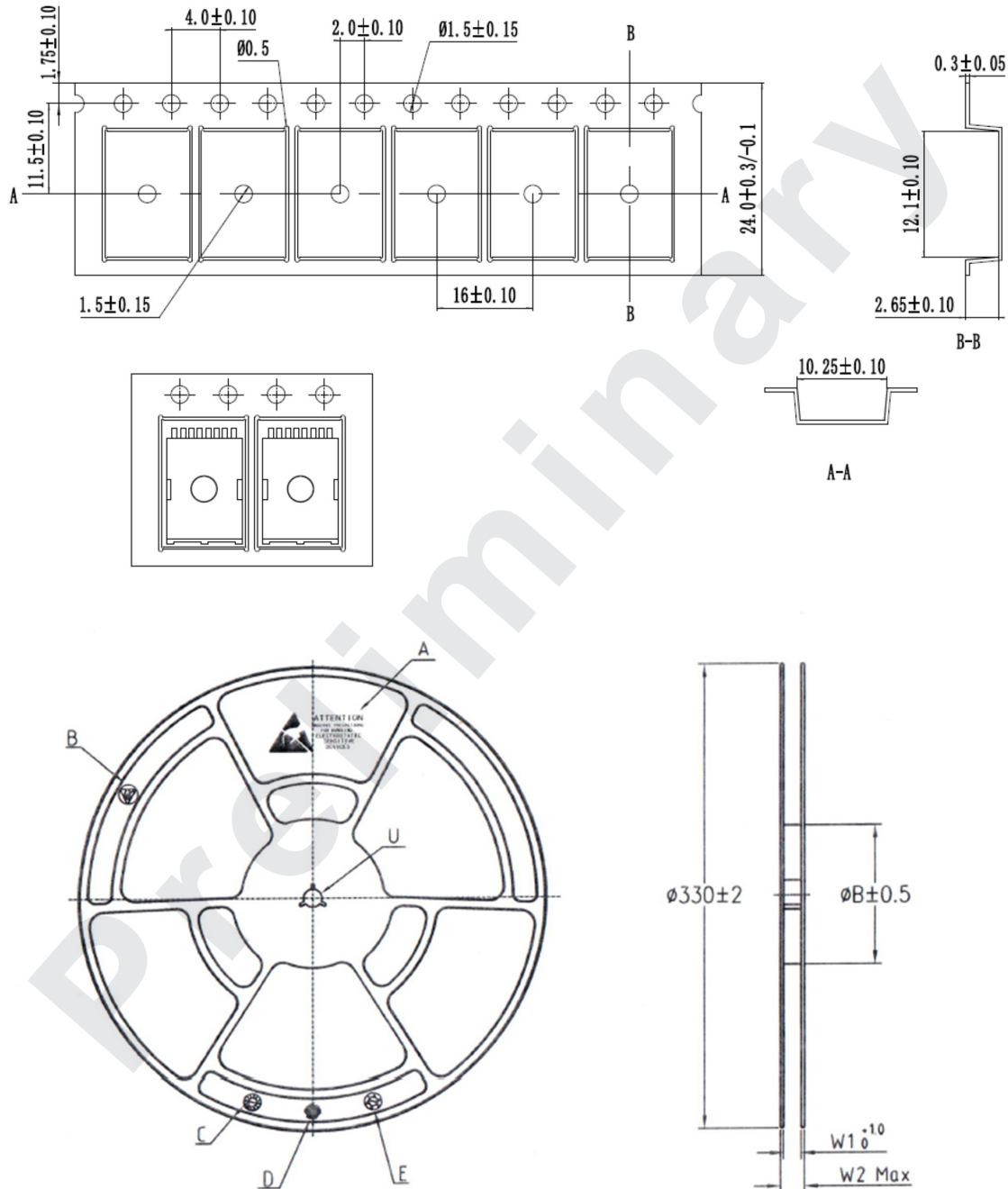


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	2.15	2.30	2.45
b	0.30	0.40	0.50
b1	0.31	0.43	0.55
b2	0.65	0.80	0.90
c	0.40	0.50	0.60
D	10.18	10.38	10.58
D1	0.50	0.70	0.90
D2	3.30REF		
D3	2.77REF		
E	9.70	9.90	10.10
E1	8.50REF		
E2	8.50REF		
E3	9.46REF		
e	1.10	1.20	1.30
H	11.48	11.68	11.88
K	4.08REF		
K1	4.18REF		
L	9.13REF		
L1	0.23REF		
L2	0.50	0.60	0.70
L3	1.00	1.20	1.40
L4	1.00	1.20	1.40
M	4.18REF		
M1	0.26REF		
M2	1.10	1.20	1.30
M3	3.10REF		
Ø	10.00REF		
e2	4.20	4.30	4.40

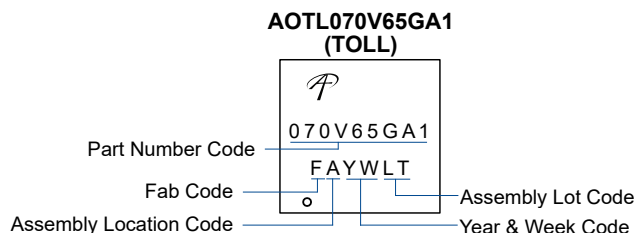
Notes:

- (1) Dimensioning and tolerancing confirm to ASME Y14.5M-1994
- (2) All dimensions are in millimeters, angles are in degrees
- (3) Coplanarity applies to the exposed heat slug as well as the terminal
- (4) Radius on terminal is optional
- (5) General tolerance: ± 0.10 mm

Tape and Reel Dimensions, TOLL



Part Marking



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